# 

Research at high Altitude on Distributed Irradiance Aboard an iNexpensive Cubesat Experiment

Test Readiness Review

Presenters: Katie Dudley, Jenny Kampmeier, Russell Bjella, Jeremy Muesing

Team Members: Brandon Antoniak, Lance Walton, David Varley, James Pavek, Alec Fiala





## Project Statement

RADIANCE will design, build, test, and deliver a 3U CubeSat-style payload to collect solar irradiance data, images, attitude information, and ambient atmospheric data on a high-altitude balloon flight.

Component Testing Subsystem Testing

## Project-Level ConOps

#### Power Up

Using external power source equivalent to 15 W of expected HiWind power



Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

Budget



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## **Baseline Design**



Project Overview

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## Functional Requirements



RADIANCE shall...

FR1: Take solar irradiance measurements.

FR2: Survive the environmental conditions of a high-altitude balloon flight up to 40 km.

- FR3: Return data.
- FR4: Determine its attitude.
- FR5: Interface with the HiWind Gondola.
- FR6: Capture images of the Sun in the visible spectrum.

The project deliverables shall include a Path-to-Space report.



Solution

Work

## Levels of Success



System	Expected Level	Details	Date
Instr.	3	Take solar irradiance measurements at better than 1.5nm resolution covering 250-1000nm Capture 1 photo/min of the Sun for full flight Provide calibration of the instrument	3/18
C&DH	3	Record solar irradiance, attitude, environmental, and housekeeping data on a durable data storage device with sufficient capacity	3/18
Thermal	3	All systems survive and operate during the thermal conditions of the full flight	3/31

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## Levels of Success



System	Expected Level	Details	Date	
	2	Determine and record attitude to 1 arcminute of accuracy relative to the sun vector	3/31	
ADS	1	Determine and record attitude to 1° of accuracy relative to the sun vector		
EPDS	1	Package operates on HiWind power supply	3/18	
Structure	1	Structure must be within 10cm x 10cm x 32cm Data is recoverable after up to 5 Gs on landing Structure can be affixed to HiWind	Done	

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## **Critical Project Elements**



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CPE	Justification	FR
Thermal Control	All components must meet thermal requirements	2
Power	Power board design is complex	5
Software	Efficient software design is critical to mission success	3
Camera, Lens	Challenging assembly to ensure in-focus images	6
Attitude Determination	Complex design, small parts, challenging hardware/software interface	4

#### No changes since MSR.





## Executive Summary



	January	February	Ma	rch	April	May
EPDS	12%		41%			
Procurement				65%		85%
Manufacturing						90 <b>9</b> 5 <mark>%</mark>
Thermal						90%100%
Software						79 <b>%5%</b>
Attitude Det.				60%		80%
Path-to-Space	0%0%			Today		
Testing		20%	40%			





Project Overview Schedule Component Testing Subsystem Testing Integration Testing

## Verification & Validation Plan



Component Testing	Subsystem Testing	Integration Testing
Verify that components operate as expected	Verify integrated operation of subsystems Model Validation	Verify integrated operation of full system Model Validation
Start Nov 21	Start Feb 22	Mar 10 — Apr 14

Project Overview Component Testing

Subsystem Testing Integration Testing



## Component Testing

Project Overview Schedule Component Testing Subsystem Testing Testing Budget

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## Purpose and Scope

Component Testing

#### Subsystem Testing

Integration Testing

Integration

Testing

- Purpose:
  - Verify components turn on, take measurements, and act according to data sheets

Component

Testing

**Subsystem** 

Testing

- Investigate need for calibration & perform calibration
- Scope:
  - Sensors and science instruments
  - Microcontroller and storage devices
  - Power system and thermal control components
- Risks Reduced:

Project

**Overview** 

Camera lens modification

Schedule

## Component Testing Schedule



## Spectrometer Calibration



- Avantes Deuterium light source
- AvaSoft calibration software
- Calibration stored on spectrometer



Wavelength (160-1000nm)

Component Testing Subsystem Testing Integration Testing

### Photodiode Test

- Single photodiode
- Measure current with multimeter
- Verify response to small angular position changes
- Higher than expected current (2.51 mA)
  - Change feedback resistance from 5 kΩ to 1 kΩ



Component Testing Subsystem Testing Integration Testing

## **Battery Capacity Testing**



Battery discharge across load resistor

- Voltage readings taken every 5 seconds
- >50W, 5 $\Omega$  resistor used

**Schedule** 

Project

**Overview** 



**Subsystem** 

Testing

Component

Testing



## Battery Discharge Testing



- >Batteries charged to ~90%
- > Tested at 0.5C discharge rate
- Linear voltage drop to ~3.25V
- Discharge test stopped at 2.5V



## External Humidity Sensor

Analog

## Measure frequency Placed on back of structure





Project Overview

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Component Testing Subsystem Testing Integration Testing

## Humidity Sensor Error

#### >Systematic error

• ~36%

Project

**Overview** 

#### Circuit produces up to 20% error

- Propagated humidity error ~70%
- Requires calibration
  - EL-USB humidity sensor
  - Accurate to 3% RH

**Schedule** 

Component

Testing





Integration

Testing

Subsystem

Testing

## Status Summary

		1
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Completed & Passed	In Progress	Upcoming
<ul> <li>Batteries (2)</li> <li>Camera</li> <li>Env. Temperature Sensor</li> <li>Env. Humidity Sensor</li> <li>Housekeeping Temperature Sensors (3)</li> <li>Raspberry Pi</li> <li>SLC Flash Drive</li> <li>MLC Flash Drive (2)</li> <li>Heaters (2)</li> <li>Photodiodes (4)</li> <li>Spectrometer Calibration</li> </ul>	<ul> <li>ND Filter</li> <li>Wire fit</li> <li>Humidity Sensor</li> <li>SLC microSD card</li> </ul>	<ul> <li>TVAC Temp Sensors (10)</li> </ul>

Component Testing Subsystem Testing



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## Subsystem Testing

Project<br/>OverviewScheduleComponent<br/>TestingSubsystem<br/>TestingIntegration<br/>TestingBudget

## Purpose and Scope



#### Subsystem Testing

#### Integration Testing

Integration

Testing

- Purpose:
  - Verify and integrate operation of subsystems, and interaction between software with hardware
  - Validate CAD model and ADS model
- Scope:
  - Power boards with batteries

Schedule

- Thermal, instrumentation, C&DH, and software
- Structural integration
- Risks Reduced:

Project

**Overview** 

• Fabrication incompatibility, improper data handling, and circuit issues

Component

Testing

Subsystem

Testing

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## Subsystem Testing Schedule



## Structure Test Summary

PurposeTest fabrication compatibility<br/>between purchased components<br/>and manufactured parts



#### **Designed Assembly**

Actual Assembly

Project Overview

Schedule

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## Sommers-Bausch Observatory

- Used for testing ADS and camera
- Sun-tracking telescope with 2 arcsec/hour drift

FR 4: RADIANCE shall determine its attitude.

FR 6: RADIANCE shall take images of the sun.





**Schedule** 

Component Testing

Subsystem Testing

Integration Testing

## ADS Subsystem Test

- Photodiodes connected to ADC and Raspberry Pi
   Collect data with
- flight software, write to flash drive
- Compare computed angle with STK model



Project Overview

Schedule

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## Ideal Results (STK)



## Power Testing: Model



#### Verify Voltage

- 3 Modeled Points
- Interfaces
  - -Battery
  - —Heater
  - -USB

Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

## FlatSat Power Board Testing





Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

## **Revision 2 Power Testing**





- Verify changes successful
- Verify power model
- Begin integration testing

Project Overview

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Component Testing Subsystem Testing

## Active Thermal System



- Verify Raspberry Pi turns heater on/off
- Verify software integration with hardware
- Confirm thermostat dead-zone

Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

## Status Summary



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Completed & Passed	In Progress	Upcoming	
<ul> <li>Structural Fit</li> <li>Power Board Rev. 1</li> </ul>	<ul> <li>Attitude Determination System</li> <li>Camera System</li> <li>Power Board Rev. 2</li> <li>Environmental Sensors with C&amp;DH and Software</li> </ul>	<ul> <li>Active Thermal Control System</li> <li>Power Board Rev. 3</li> </ul>	

Project<br/>OverviewScheduleComponent<br/>TestingSubsystem<br/>TestingIntegration<br/>TestingBudget



## Integration Testing

Project Overview Schedule Component Testing Testing Integration Testing Budget 36
### Purpose and Scope

Component Testing

#### Subsystem Testing

#### Integration Testing

- Purpose:
  - Verify and demonstrate integrated operation of full system
  - Validate SolidWorks thermal, C&DH storage capacity, and timing models
- Scope:
  - Includes all hardware, electrical components, and software
  - FlatSat Tabletop Integration and Environmental Testing
- Risks Reduced:

Project

**Overview** 

Violating operational temperature bounds

Schedule

- Data overwrite error
- Software lock-up

### Integration Testing Schedule





### FlatSat Tabletop Integration

48-hour continuously staffed test March 17 to March 19

DAQ System:

- Flight system writes data from all sensors to onboard storage
- NI 6009 DAQ system to record voltages
- Manual backup of voltage measurements
- Heartbeat messages to terminal

FlatSat Test Plan for RADIANCE	1		
Written by: Katelyn Dudley			
Modified: Mar 1			
Required Components by Subsystem			
Instrumentation		uit	
<ul> <li>Camera with mount, lens adjustment, and Neutral Density filter</li> </ul>			
<ul> <li>Spectrometer</li> </ul>			drive,
<ul> <li>ADS: photodiodes, mount, transimpedance amps, ADCs</li> </ul>			
<ul> <li>Environmental temperature and humidity sensor</li> </ul>			
Power			
<ul> <li>Batteries</li> </ul>			
<ul> <li>Power board (Rev 2, flight or FlatSat board ok)</li> </ul>			
C&DH/Software	Ŧ		ad
<ul> <li>Flight Raspberry Pi with SLC microSD loaded with OS and flight software (with static IP set and recorded)</li> </ul>			
<ul> <li>2 MLC flash drives and SLC flash drive</li> </ul>			
<ul> <li>Ethernet cable with access to ethernet port</li> </ul>			
Thermal			
<ul> <li>Housekeeping temperature sensors on SLC flash drive and each battery</li> </ul>			ights
<ul> <li>Heaters can be plugged in and connected, but should never turn on in lab</li> </ul>		ncy	
environment. Place on particle board or wood in case they heat up unexpectedly			
(this would be a reason to call for help and debug)			
Structure	et		
<ul> <li>Not needed</li> </ul>	SL		
Other Materials and Equipment			
<ul> <li>Power Supply to provide 28V, 15W</li> </ul>			
<ul> <li>Stay away from GPS 4303 supply on station by cabinet 1</li> </ul>	IX		
Multimeter			
<ul> <li>Kapton tape disks (to attach the housekeeping temp sensors)</li> </ul>			
<ul> <li>NI-6009 with USB cable</li> </ul>	ľ		
Modified Basic Voltage VI			
Computer with LabView			
<ul> <li>Assorted banana cables, alligator clips, breadboard, jumper wire kit</li> </ul>	out		
		L	
	У		
	her		
	J		
<ul> <li>Plug data storage drives into computer. Delete files, and record storage capacity</li> </ul>	/		
properties			
Ending Procedures (Last Shift Only)			
Ending Procedures (East Shint Only)			,

Schedule

Component Testing Subsystem Testing Integration Testing

#### Thermal Vacuum Chamber

Component

Testing

Subsystem

Testing

FR 2: The system shall survive the environmental conditions of flight.

- TVAC at HAO NCARWeek of March 20
- Validate thermal models for cruise

Schedule

- >Chamber ratings:
  - 270 Pa, -20°C
- >Our needs:

Project

**Overview** 

• 200 Pa, 5°C



Integration

Testing

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Unacceptable risk to expose spectrometer to ENV tests
Mimic mass (174 g), conductivity, and heat output
1D heater rated to 20W inside milled-out aluminum block

Component

Testing

**Subsystem** 

Testing

Integration

Testing

Project

**Overview** 

**Schedule** 

#### Environmental Chamber



FR 2: The system shall survive the environmental conditions of flight.



- Payload will experience two full ascent profiles
- Narrow availability for chamber use
- Requires constant staffing

Spectrometer analog will be used to avoid damaging expensive instrumentation

Project Overview

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#### Environmental Chamber

Component

Testing

- External DAQ and Power
- DAQ system: 10 temperature sensors in chamber sending data to DAQ-specific Raspberry Pi

**Schedule** 

Project

**Overview** 

- System will function as in flight (minus spectrometer)
- Wires feed through foam insulated port

Integration

Testing

x = Temperature Sensor

**Subsystem** 

Testing

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#### Environmental Chamber





>ENV chamber only takes linear inputs

Temperature profile linearized to be harsher than reality

Start test with 60 minutes at -10°C







Project Overview Component Testing Subsystem Testing

### Testing and Risk Mitigation



Element	Value	Test
Overheating	5	TVAC
Frost on optics	5	Acceptable Risk
Heater failure	3	TVAC
Drive hardware failure	4	Acceptable Risk
Temporary power failure	3	FlatSat (Error Handling)
Software data write failure	2	FlatSat (Error handling)
Bit flip	2	Acceptable Risk
Drive connection failure	2	Acceptable Risk
Camera oversaturation	2	SBO
Pi software failure	1	FlatSat

Project Overview

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#### Status Summary



Completed & Passed	In Progress	Upcoming
• None yet	• None yet	<ul> <li>FlatSat Tabletop Integration</li> <li>Thermal Vacuum Chamber</li> <li>Environmental Chamber</li> </ul>

Project Overview Schedule Component Subsystem Testing Testing

Integration Testing



Project Overview Schedule Component Testing Subsystem Testing Integration Testing



#### Procurement Status



Subsystem	Projected Cost	Procured	To be Procured	Margin (%)	Effect on Budget
C&DH	\$ 167	\$ 149	_	—	+\$ 18
Sensors	\$ 203	\$ 127	—	—	+\$ 76
Instrumentation	\$2988	\$3022	_	—	-\$ 34
Power	\$ 662	\$ 374	\$ 282	\$ 56	-\$ 50
PM	\$ 84	_	\$ 84	—	_
Structure	\$ 418	\$ 223	\$ 4	\$ 6	+\$185
Testing	\$ 250	_	\$ 93	\$ 157	_
Thermal	\$ 66	\$ 36	_	—	+\$ 30
TOTAL	\$4613	\$3931	\$ 463	\$ 219 (47%)	+\$225

Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

#### Budget Status

Estimate	Cost
CDR Estimate	\$4920
MSR Estimate	\$4634
TRR Estimate	\$4613



Item	Status	Notes
Avantes calibration hardware	Procured	Free
Professional board population	Planned	Included in budget
AIAA conference registration	Investigated	\$270
Expedited Shipping	Optional	—

Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing

#### Thank you!

#### We welcome your feedback!



Project Overview

Schedule

Component Testing Subsystem Testing Integration Testing



### BACKUP





### Requirements and Models



Requirement	Model	Test	Date
FR 1: Take solar irradiance measurements		Spectrometer Calibration	Feb 19
FR 2: Survive environmental conditions	SolidWorks Thermal	Thermal Vacuum Chamber Environmental Chamber	Wk of Mar 20 Mar 31, Apr 5
FR 3: Return data	C&DH, Storage	FlatSat Tabletop Integration	Mar 10-12
FR 4: Determine off-sun angle	Attitude	Photodiode Testing at SBO	Mar 2-8
FR 5: Interface with HiWind		Inspection	Continuous
FR 6: Capture images of the sun		Camera Testing at SBO	Mar 2-8



### Other Testing

#### **Heaters**

- Check resistance
- Check heat production
- Visually inspect for damage

#### **Temperature Sensors**

- Check 1Wire data operability
- Quantify Temperature sensor error with known sources (Boiling water/Ice)

#### **Storage Devices**

- Change formatting to EXT3 with Journaling
- Check data read/write
- Check unplugged data storage
- Check memory volume

#### Wire Fit

- Check wire turn needs
- Check slot clearance width and height
- Smooth possible abrasive corners

Component Testing Subsystem Testing

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#### Internal Temp Sensors



One-wire interface

Placement
SLC drive
One per battery



Internal Temperature Sensors

Placed hand on sensor



Note: Uncertainty is 0.5 °C on each measurement

Project Overview

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Component Testing

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Subsystem Testing Integration Testing

#### External Temp Sensor



# I2C interface Placed on back of structure





Project Overview

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#### Structure Test Results

Test fit resulted in a few changes:

Camera mount had to be 3D printed
Longer screws needed in a couple places
Using two screws for camera mounting
Minor changes to photodiode array to fit boards
New threads for neutral density filter



#### Attitude Determination System

- Photodiode array (heritage from MinXSS)
  - 4 photodiodes offset at 45 degrees from boresight determine relative position of sun
- Success Levels
  - Level 1: ± 1° accuracy
  - Level 2: ± 1 arcminute accuracy

### FR 4: RADIANCE shall determine its attitude.



Project Overview

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#### **ADS Test Procedure**



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#### Telescope Mount for ADS Test





#### Camera/Lens System

- Images provide context for spectrometer data
- Using neutral density filter
  - Optical density of 1.5
  - Protects camera electronics from saturation/damage
  - 6.3° field-of-view

## FR 6: RADIANCE shall take images of the sun.



Schedule

Component Testing Subsystem Testing Integration Testing

#### Neutral Density Filter Test





#### Power Testing

#### Purpose

#### Resources

Verify Voltage/Power draw

Interfaces

- **>**Pi
- Battery
- Heater

Trudy's and Bobby's labs

- Power Source
- > Multimeters

#### **Risks Reduced**

Variable input voltage (28-33V)

Voltage regulation

Project Overview

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Component Testing Subsystem Testing







- Unacceptable risk to expose spectrometer to environmental tests
- Mimic conductive properties, mass, and power output
  - Al 6061-T6, 174 g, 1.25 W
- 1D heater rated to 20W inside milled-out aluminum block





### Data Storage Model – MLC

Measurement	Size/data point	Frequency	Total
Camera images	1.8 MB (max)	1/60 Hz	40.5 GB

### Data Storage Model – SLC

Measurement	Size/data point	Frequency	Total
Spectrometer	16.384 kB	1 Hz	10.55 GB
External temperature	4 B	1 Hz	5.273 MB
Internal temps (x6)	24 B	1 Hz	31.638 MB
Humidity	4 Botal: 10.64 GB	1 Hz	5.273 MB
Photodiode (x4)	32 B	1 Hz	42.1875 MB
Sun angle	4 B	1 Hz	5.273 MB



## Software System Testing Status

- System testing not started
- Will start after unit testing is complete



### Unit Testing Status

- Unit testing started
- 1/10 tests written





### Static Testing Status

- Static testing tests code without running
- Fixed 3/3 errors

10/12 files checked 73% done Checking RADIANCE-main/src/sensors/spectrometer.cc... Checking RADIANCE-main/src/sensors/spectrometer.cc: AS5216\_EXPORTS... Checking RADIANCE-main/src/sensors/spectrometer.cc: USE\_POSTMESSAGE... Checking RADIANCE-main/src/sensors/spectrometer.cc: USE\_POSTMESSAGE... Checking RADIANCE-main/src/sensors/spectrometer.cc: \_M\_X64... 11/12 files checked 97% done Checking RADIANCE-main/src/systemhaltexception.cc... 12/12 files checked 100% done


## Procured Budget Status



Subsystem	Projected Cost	Procured	To be Procured	Effect on Budget
C&DH, Inst.	\$3424	\$3304		+\$ 120
Power	\$ 662	\$ 281	\$ 382	
PM	\$ 84		\$ 84	
Structure	\$ 418	\$ 223	\$ 10	+\$ 185
Testing	\$ 250		\$ 250	
TOTAL	\$4850	\$3808	\$ 726	+\$ 205

CDR Total (with margin and excess): \$4,920

